RZ/T2H, RZ/N2H XDP Package

Version 1.0.1

Release Note

R01US0724EJ0101
Rev. 1.01
Dec. 23, 2024

Introduction

This release note describes the contents and important points of the RZ/T2H, RZ/N2H XDP Package.

Please also refer to the following documents that describe the Board Support Package (hereinafter referred to as “BSP”) and the instruction to build BSP and boot the evaluation boards.

- r01us0681ej0101-rz-t2h-n2h(Release_Note_RZT2H_N2H).pdf
- r01us0682ej0101-rz-t2h-n2h(Linux_Start-up_Guide_RZ/T2H_N2H).pdf

Contents

1. Release Items

- **Name and version**
  RZ/T2H, RZ/N2H XDP Package Version 1.0.1

- **Target board**
- RZ/T2H Evaluation Board
- RZ/N2H Evaluation Board

- **Functions**
  XDP (eXpress Data Path)

- **File contents**
  BSP is delivered by the files listed in Table 1.

Table 1. RZ/T2H, RZ/N2H XDP Package

RZ/T2H, RZ/N2H XDP Package v1.0.1

File	Description
RTK0EF0177Z02000ZJ-v1.0.1.zip (*)	XDP Package. This file includes the Yocto recipe and the necessary document.
meta-rz-dpdk_v1.0.1.tar.gz	Yocto recipe to build the test tool of XDP.
r01us0724ej0101-rz-t2h-n2h (XDP_Package_Release_Note).pdf	This document.
r11an0831ej0101-rz-t2h-n2h(XDP_AppNote).pdf	This file describes how to use XDP.

Basic Packages of BSPv1.0.1

File	Description
RTK0EF0177Z00002ZJ-v1.0.1.zip (*)	Board Support Package. This file includes the **Yocto recipe packages** and the necessary documents.
rzt2h_n2h_bsp_v1.0.1.tar.gz	**Yocto recipe packages**
- HDR NM - Flash_Programmer_SCIF_CR52_RZT2H_EVK.mot	Flash Programmer. These are used for writing the bootloaders on the evaluation board.
r01us0681ej0100-rz-t2h-n2h(Release_Note_RZT2H_N2H).pdf	BSP release note.
R01us0682ej0100-rz-t2h-n2h(Linux_Start-up_Guide_RZ/T2H_N2H).pdf	Documents describing booting method and the required settings of bootloader for RZ/T2H, RZ/N2H.

(*) These packages are provided “AS IS” with no warranty and the license which is described in the source code. Please check the contents of the license, then consider the applicability to the product carefully.

2. Components

The components which are commonly used in this release are listed in the following table. Please also refer to the manifest file for details. The manifest file is created to following path after building the images:

Example:

```
$WORK/build/tmp/deploy/images/rzt2h-dev/core-image-minimal-rzt2h-dev.manifest
```

Or

```
$WORK/build/tmp/deploy/images/rzn2h-dev/core-image-minimal-rzn2h-dev.manifest
```

Table 2. Versions of commonly used components

Components	**BSP v1.0.0**	**BSP v1.0.1**
Linux kernel	5.10.145-cip17	5.10.145-cip17
GCC	8.3.0 (Arm GCC 8.3-2019.03)	8.3.0 (Arm GCC 8.3-2019.03)
busybox	1.30.1	1.30.1
openssl	1.1.1n	1.1.1n

3. Changes

The following table lists the changes from the previous version.

Table 3. Changes from XDP Package v1.0.0 to v1.0.1

Features	Description
Package	- Newly support RZ/N2H evaluation board.

4. Restriction

None.

5. Notes

None.

6. Revision History

Rev.	Date	Description	
		Page	Summary
1.00	Nov. 26, 2024	-	First edition issued.
1.01	Dec. 23, 2024	-	Newly support RZ/T2H, RZ/N2H BSP v1.0.1.

Website and Support

Renesas Electronics Website
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